

SN54LVTH162245... WD PACKAGE

SN74LVTH162245... DGG OR DL PACKAGE

(TOP VIEW)

1DIR 1

1B1 2

1B2 3

GND 4

1B3 5

1B4 🛛 6

V_{CC} [] 7

1B5 🛛 8

1B6 🛛 9

GND 110

1B7 11 1B8 12

2B1 11 13

2B2 14

GND 115

2B3 🛛 16

2B4 17

V_{CC} [] 18

2B5 🛛 19

2B6 20

GND 21

2B7 🛛 22

2B8 23

2DIR 24

48 🛛 1 OE

47 🛛 1A1

46 1A2

45 GND

44 1A3

43 **1**A4

42 V_{CC}

41 🛛 1A5

40 🛛 1A6

39 GND

38 🛛 1A7

37 **1**A8

36 2A1

35 🛛 2A2

34 GND

33 2A3

32 2A4

31 VCC

30 2A5

29 2A6

28 GND

27 27 2A7

26 2A8

25 20E

FEATURES

- Members of the Texas Instruments Widebus™ Family
- A-Port Outputs Have Equivalent 22- Ω Series **Resistors. So No External Resistors Are** Required
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Distributed V_{CC} and GND Pins Minimize **High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

The 'LVTH162245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively isolated.

The logic levels of the direction-control (DIR) input and the output-enable (\overline{OE}) input activate either the B-port outputs or the A-port outputs or place both output ports into the high-impedance mode. The device transmits data from the A bus to the B bus when the B-port outputs are activated, and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports is always active and must have a logic HIGH or LOW level applied to prevent excess I_{CC} and I_{CCZ} .

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent $22 \cdot \Omega$ series resistors to reduce overshoot and undershoot.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. Widebus is a trademark of Texas Instruments.

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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

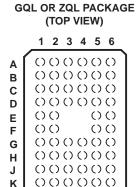
When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

T _A	PACKAGE	<u>=</u> (1)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	FBGA – GRD	Reel of 1000	74LVTH162245GRDR	11.0045
	FBGA – ZRD (Pb-free)	Reel of 1000	74LVTH162245ZRDR	– LL2245
		Tube of 25	SN74LVTH162245DL	
	SSOP – DL	1 UDE 01 25	SN74LVTH162245DLG4	LVTH162245
	550P - DL	Reel of 1000	SN74LVTH162245DLR	
–40°C to 85°C		Reel of 1000	74LVTH162245DLRG4	
			SN74LVTH162245DGGR	
	TSSOP – DGG	Reel of 2000	74LVTH162245DGGRG4	LVTH162245
			74LVTH162245GRE4	
	VFBGA – GQL	Reel of 1000	SN74LVTH162245KR	- LL2245
	VFBGA – ZQL (Pb-free)	Reel of 1000	74LVTH162245ZQLR	
–55°C to 125°C	CFP – WD	Tube	SNJ54LVTH162245WD	SNJ54LVTH162245WD

ORDERING INFORMATION

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



TERMINAL ASSIGNMENTS⁽¹⁾ (56-Ball GQL/ZQL Package)

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1 OE
в	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V _{CC}	V _{CC}	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
Е	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
н	2B5	2B6	V _{CC}	V _{CC}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
Κ	2DIR	NC	NC	NC	NC	2 <mark>0E</mark>

(1) NC - No internal connection

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TERMINAL ASSIGNMENTS⁽¹⁾ (54-Ball GRD/ZRD Package)

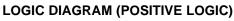
	1	2	3	4	5	6
Α	1B1	NC	1DIR	1 <mark>0E</mark>	NC	1A1
В	1B3	1B2	NC	NC	1A2	1A3
С	1B5	1B4	V _{CC}	V _{CC}	1A4	1A5
D	1B7	1B6	GND	GND	1A6	1A7
Е	2B1	1B8	GND	GND	1A8	2A1
F	2B3	2B2	GND	GND	2A2	2A3
G	2B5	2B4	V _{CC}	V _{CC}	2A4	2A5
н	2B7	2B6	NC	NC	2A6	2A7
J	2B8	NC	2DIR	2 <mark>0E</mark>	NC	2A8

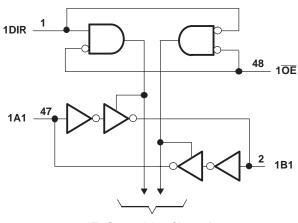
(1) NC - No internal connection

FUNCTION TABLE⁽¹⁾ (EACH 8-BIT SECTION)

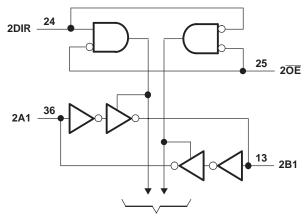
CONTRO	L INPUTS	OUTPUT C	IRCUITS	OPERATION
OE	DIR	A PORT	B PORT	OPERATION
L	L	Enabled	Hi-Z	B data to A bus
L	Н	Hi-Z	Enabled	A data to B bus
Н	Х	Hi-Z	Hi-Z	Isolation

(1) Input circuits of the data I/Os always are active.

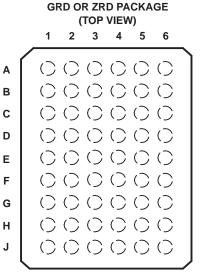




To Seven Other Channels



To Seven Other Channels



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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V _{CC}	Supply voltage range		-0.5	4.6	V	
VI	Input voltage range ⁽²⁾		-0.5	7	V	
Vo	Voltage range applied to any output in the high-ir	mpedance or power-off state ⁽²⁾	-0.5	7	V	
Vo	Voltage range applied to any output in the high s	tate ⁽²⁾	-0.5	V _{CC} + 0.5	V	
		SN54LVTH162245 (B port)		96		
I _O	Current into any output in the low state	SN74LVTH162245 (B port)		128	mA	
		A port		30		
		SN54LVTH162245 (B port)		48		
lo	Current into any output in the high state ⁽³⁾	SN74LVTH162245 (B port)		64	mA	
		A port		30		
I _{IK}	Input clamp current	V ₁ < 0		-50	mA	
I _{OK}	Output clamp current	V _O < 0		-50	mA	
		DGG package		70		
0	Deckage thermal impedance (4)	DL package		63	°C/W	
θ_{JA}	Package thermal impedance ⁽⁴⁾	GQL/ZQL package		42	-0/00	
		GRD/ZRD package	36]	
T _{stg}	Storage temperature range	· · · · · · · · · · · · · · · · · · ·	-65	150	°C	

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. (2)

(3) This current flows only when the output is in the high state and $V_O > V_{CC}$. (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

			SN54LVTH	162245	SN74LVTH1	62245	UNIT
			MIN	MAX	MIN	MAX	UNIT
V _{CC}	Supply voltage		2.7	3.6	2.7	3.6	V
V _{IH}	High-level input voltage		2		2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage			5.5		5.5	V
	Lich lovel output ourrent	A port		-12		-12	~
юн	High-level output current	B port		-24		-32	mA
		A port		12		12	
IOL	Low-level output current	B port		48		64	mA
$\Delta t / \Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t / \Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

		TEST		SN54	LVTH162245		SN74L	VTH16224	45	
PARA	AMETER	TESTC	ONDITIONS	MIN	TYP ⁽¹⁾ N	IAX	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK}		V _{CC} = 2.7 V,	I _I = -18 mA		-	-1.2			-1.2	V
	Amont	$V_{CC} = 2.7 V \text{ to } 3.6 V,$	I _{OH} = -100 μA	$V_{CC} - 0.2$			$V_{CC} - 0.2$			
	A port	V _{CC} = 3 V,	I _{OH} = -12 mA	2			2			
\ <i>\</i>		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	$V_{CC} - 0.2$			$V_{CC} - 0.2$			V
V _{OH}	Durant	V _{CC} = 2.7 V,	I _{OH} = -8 mA	2.4			2.4			v
	B port	V _{CC} = 3 V	I _{OH} = -24 mA	2						
		$v_{\rm CC} = 3 v$	I _{OH} = -32 mA				2			
	A port	V_{CC} = 2.7 V to 3.6 V,	I _{OL} = 100 μA			0.2			0.2	
	A poit	$V_{CC} = 3 V,$	I _{OL} = 12 mA			0.8			0.8	
		V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2			0.2	
V _{OL}		$v_{\rm CC} = 2.7 v$	I _{OL} = 24 mA			0.5			0.5	V
V OL	B port		I _{OL} = 16 mA			0.4			0.4	v
	D poir	$V_{CC} = 3 V$	I _{OL} = 32 mA			0.5			0.5	
		V _{CC} = 5 V	I _{OL} = 48 mA		().55				
			I _{OL} = 64 mA						0.55	
	Control	$V_{CC} = 3.6 V,$	$V_I = V_{CC}$ or GND			±1			±1	
	inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10	
l _l	A		V _I = 5.5 V			20			20	μA
	A or B port ⁽²⁾	$V_{CC} = 3.6 V$	$V_{I} = V_{CC}$			5			5	
			V ₁ = 0			-10			-10	
I _{off}	_	$V_{CC} = 0,$	$V_{I} \text{ or } V_{O} = 0 \text{ to } 4.5 \text{ V}$						±100	μΑ
		$V_{CC} = 3 V$	V _I = 0.8 V	75			75			
I _{I(hold)}	A or B		V ₁ = 2 V	-75			-75			μA
((1010)	port	V _{CC} = 3.6 V, ⁽³⁾	$V_{I} = 0$ to 3.6 V						500 -750	•
I _{OZPU}		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, V _O = OE = don't care	= 0.5 V to 3 V,		±10	0 ⁽⁴⁾			±100	μΑ
I _{OZPD}		$V_{CC} = 1.5 \text{ V to } 0, \text{ V}_{O} = OE = \text{don't care}$			±10	0 ⁽⁴⁾			±100	μA
		V _{CC} = 3.6 V,	Outputs high		().19			0.19	
I _{CC}		$I_0 = 0,$	Outputs low			5			5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		().19			0.19	
$\Delta I_{CC}^{(5)}$		$V_{CC} = 3 V \text{ to } 3.6 V,$ One input at $V_{CC} - 0.0$ Other inputs at V_{CC} of	6 V, r GND			0.3			0.2	mA
CI		$V_I = 3 V \text{ or } 0$			4			4		pF
Cio		$V_0 = 3 V \text{ or } 0$			10			10		pF

 All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
 Unused pins at V_{CC} or GND
 This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to minimum. another.

On products compliant to MIL-PRF-38535, this parameter is not production tested. (4)

(5) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

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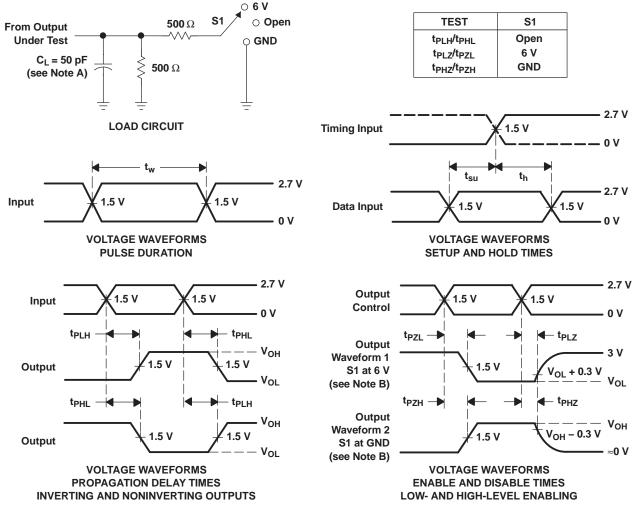
Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

			SN	54LVTH	16224	5		SN74L	VTH16	2245		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3 ± 0.3	V _{CC} = 3.3 V ± 0.3 V		V_{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	TYP ⁽¹⁾	MAX	MIN	MAX	
t _{PLH}	А	В	1	3.5		4	1	2.3	3.3		3.7	ns
t _{PHL}	A	В	1	3.5		3.9	1	2.2	3.3		3.5	115
t _{PLH}	В	А	1	4.3		5.3	1	2.8	4		4.6	ns
t _{PHL}	В	~	1	4.2		4.5	1	2.5	3.4		3.6	115
t _{PZH}	OE	В	1	4.8		5.9	1	2.8	4.6		5.4	ns
t _{PZL}	UE	В	1	4.8		5.5	1	3	4.6		5.2	115
t _{PZH}	OE	А	1	5.5		7.2	1	3.3	5.3		6.3	ns
t _{PZH}	ÜE	A	1	5.4		6.4	1	3.3	5.1		5.8	115
t _{PHZ}	OE	В	1.5	5.5		5.8	1.5	3.8	5.2		5.5	ns
t _{PLZ}	UE	В	1.5	5.5		5.8	1.5	3.5	5.1		5.4	115
t _{PHZ}	ŌĒ	А	1.5	5.8		6.5	1.5	4	5.6		5.9	ns
t _{PLZ}	UE	A	1.2	6.3		6.3	1.5	3.8	5.5		5.5	115
t _{sk(LH)}									0.5			ns
t _{sk(HL)}									0.5			115

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25^{\circ}C.

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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns. t_f \leq 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9678001QXA	ACTIVE	CFP	WD	48	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9678001QX A SNJ54LVTH16224 5WD	Samples
5962-9678001VXA	ACTIVE	CFP	WD	48	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9678001VX A SNV54LVTH16224 5WD	Samples
74LVTH162245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH162245	Samples
74LVTH162245GRE4	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH162245	Samples
SN74LVTH162245DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH162245	Samples
SN74LVTH162245DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH162245	Samples
SN74LVTH162245DLG4	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH162245	Samples
SN74LVTH162245DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH162245	Samples
SNJ54LVTH162245WD	ACTIVE	CFP	WD	48	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9678001QX A SNJ54LVTH16224 5WD	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



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⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LVTH162245, SN54LVTH162245-SP, SN74LVTH162245 :

- Catalog: SN74LVTH162245, SN54LVTH162245
- Enhanced Product: SN74LVTH162245-EP, SN74LVTH162245-EP
- Military: SN54LVTH162245
- Space: SN54LVTH162245-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH162245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74LVTH162245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH162245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74LVTH162245DLR	SSOP	DL	48	1000	367.0	367.0	55.0

MECHANICAL DATA

MCFP010B - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL FLATPACK

WD (R-GDFP-F**)

48 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only
 - E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 - GDFP1-F56 and JEDEC MO-146AB



DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not

- exceed 0.15 mm per side. 4. Reference JEDEC registration MO-153.



DGG0048A

DGG0048A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DGG0048A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate

design recommendations. 8. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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